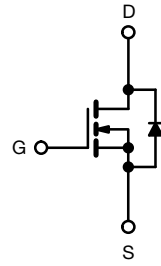


## Power MOSFET



N-Channel MOSFET

### FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS\***  
Available

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

PRODUCT SUMMARY	
$V_{DS}$ (V)	250
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$ 0.45
$Q_g$ max. (nC)	41
$Q_{gs}$ (nC)	6.5
$Q_{gd}$ (nC)	22
Configuration	Single

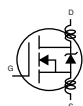

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF634PbF

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)					
PARAMETER	SYMBOL		LIMIT	UNIT	
Drain-source voltage	$V_{DS}$		250	V	
Gate-source voltage	$V_{GS}$		$\pm 20$		
Continuous drain current	$V_{GS}$ at 10 V	$T_C = 25\text{ }^\circ\text{C}$	8.1	A	
		$T_C = 100\text{ }^\circ\text{C}$	5.1		
Pulsed drain current <sup>a</sup>	$I_{DM}$		32		
Linear derating factor			0.59	W/ $^\circ\text{C}$	
Single pulse avalanche energy <sup>b</sup>	$E_{AS}$		300	mJ	
Repetitive avalanche current <sup>a</sup>	$I_{AR}$		8.1	A	
Repetitive avalanche energy <sup>a</sup>	$E_{AR}$		7.4	mJ	
Maximum power dissipation	$T_C = 25\text{ }^\circ\text{C}$		$P_D$	74	W
Peak diode recovery dV/dt <sup>c</sup>			dV/dt	4.8	V/ns
Operating junction and storage temperature range	$T_J, T_{stg}$		-55 to +150	$^\circ\text{C}$	
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s		300		
Mounting torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 7.3\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 8.1\text{ A}$  (see fig. 12)
- $I_{SD} \leq 8.1\text{ A}$ ,  $dI/dt \leq 120\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case

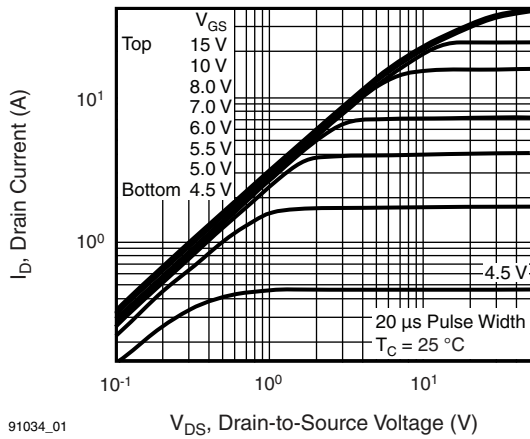
THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	62	°C/W
Case-to-sink, flat, greased surface	$R_{thCS}$	0.50	-	
Maximum junction-to-case (drain)	$R_{thJC}$	-	1.7	

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNIT	
<b>Static</b>							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		250	-	- V	
$V_{DS}$ temperature coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = 1\text{ mA}$		-	0.37	- $V/^\circ\text{C}$	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0 V	
Gate-source leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100\text{ nA}$	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 250\text{ V}, V_{GS} = 0\text{ V}$		-	-	25 $\mu\text{A}$	
		$V_{DS} = 200\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250 $\mu\text{A}$	
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 5.1\text{ A}^b$	-	-	0.45 $\Omega$	
Forward transconductance	$g_{fs}$	$V_{DS} = 50\text{ V}, I_D = 5.1\text{ A}^b$		1.6	-	- S	
<b>Dynamic</b>							
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$ , see fig. 5		-	770	-	
Output capacitance	$C_{oss}$			-	190	-	pF
Reverse transfer capacitance	$C_{rss}$			-	52	-	
Total gate charge	$Q_g$	$V_{GS} = 10\text{ V}$	$I_D = 5.6\text{ A}, V_{DS} = 200\text{ V}$ , see fig. 6 and 13 <sup>b</sup>	-	-	41	
Gate-source charge	$Q_{gs}$			-	-	6.5	nC
Gate-drain charge	$Q_{gd}$			-	-	22	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 125\text{ V}, I_D = 5.6\text{ A}, R_g = 12\text{ }\Omega, R_D = 22\text{ }\Omega$ , see fig. 10 <sup>b</sup>		-	9.6	-	
Rise time	$t_r$			-	21	-	ns
Turn-off delay time	$t_{d(off)}$			-	42	-	
Fall time	$t_f$			-	19	-	
Gate input resistance	$R_g$	$f = 1\text{ MHz}$ , open drain		0.6	-	2.9 $\Omega$	
Internal drain inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.5	-	
Internal source inductance	$L_S$			-	7.5	-	nH
<b>Drain-Source Body Diode Characteristics</b>							
Continuous source-drain diode current	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode 		-	-	8.1	
Pulsed diode forward current <sup>a</sup>	$I_{SM}$			-	-	32	A
Body diode voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = 8.1\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	2.0 V	
Body diode reverse recovery time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = 5.6\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	220	440 ns	
Body diode reverse recovery charge	$Q_{rr}$			-	1.2	2.4 $\mu\text{C}$	
Forward turn-on time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

**Notes**

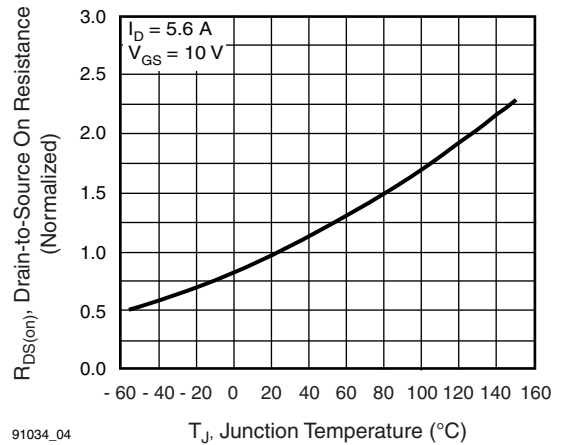
- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)  
 b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\text{ }\%$

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



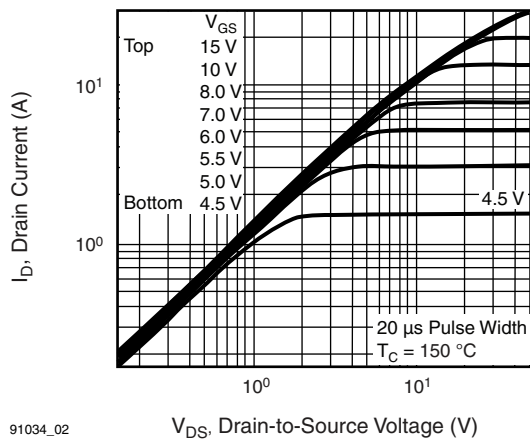
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**Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^\circ\text{C}$**



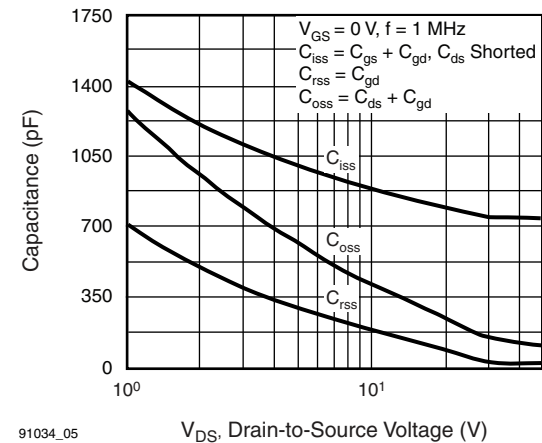
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**Fig. 4 - Normalized On-Resistance vs. Temperature**



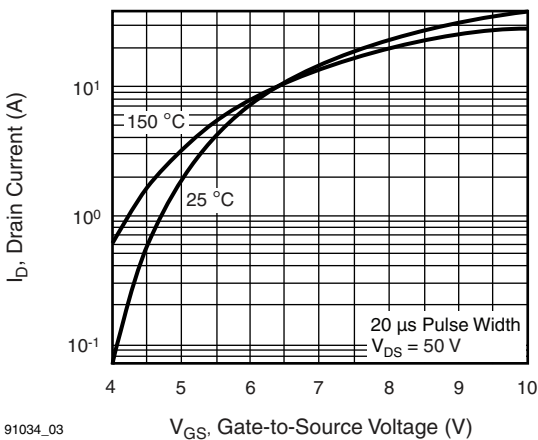
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**Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^\circ\text{C}$**



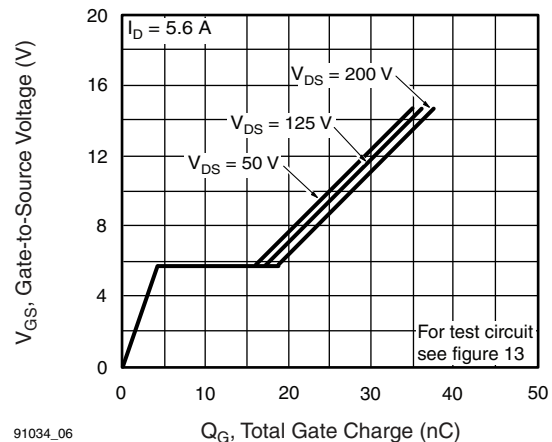
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**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



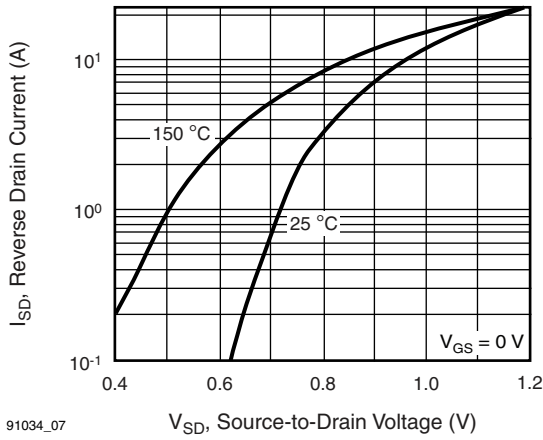
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**Fig. 3 - Typical Transfer Characteristics**



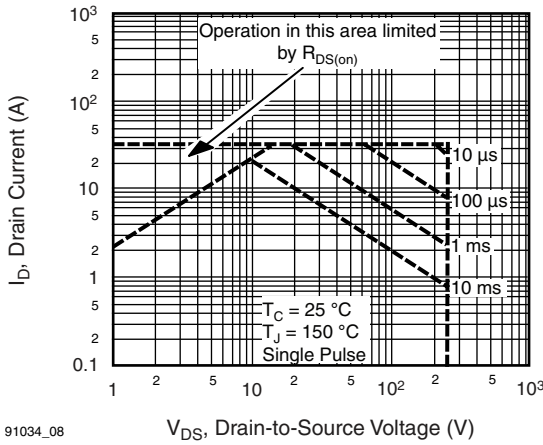
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**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



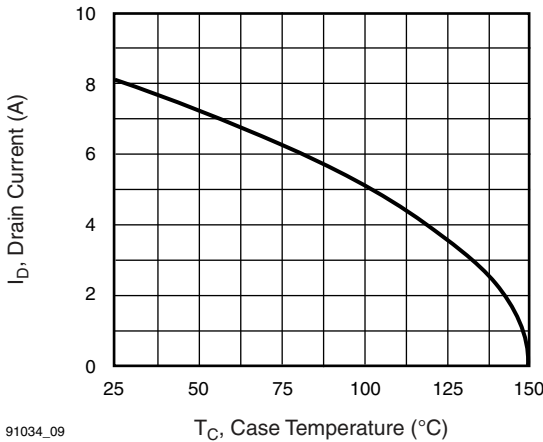
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Fig. 7 - Typical Source-Drain Diode Forward Voltage



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Fig. 8 - Maximum Safe Operating Area



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Fig. 9 - Maximum Drain Current vs. Case Temperature

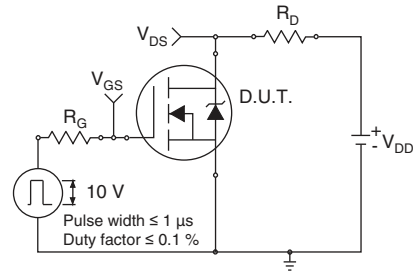


Fig. 10a - Switching Time Test Circuit

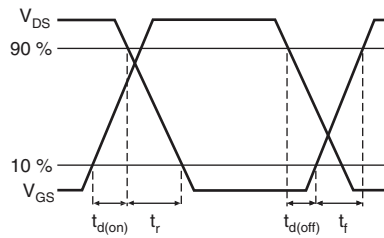


Fig. 10b - Switching Time Waveforms

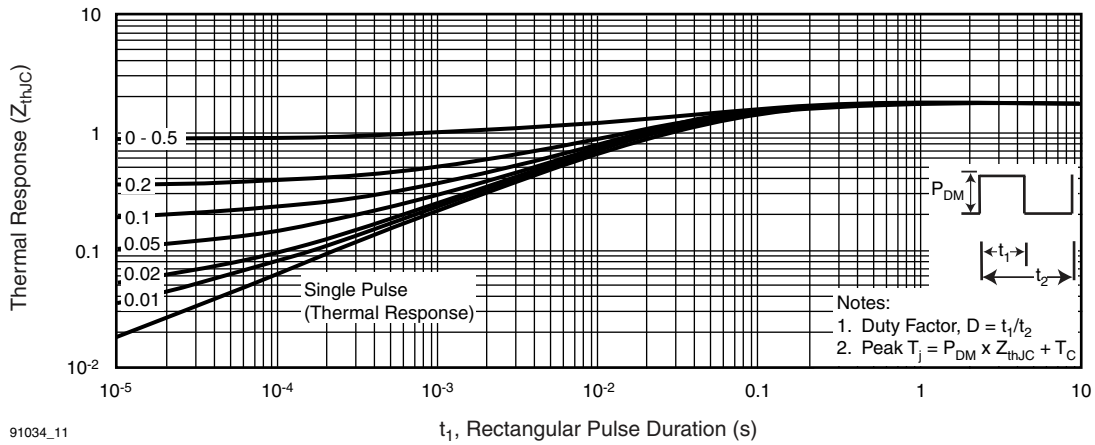


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

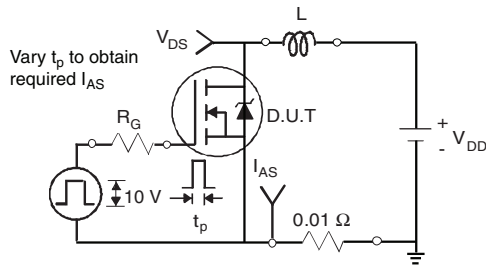


Fig. 12a - Unclamped Inductive Test Circuit

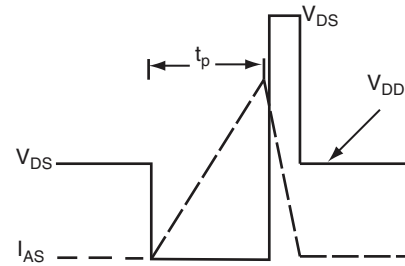


Fig. 12b - Unclamped Inductive Waveforms

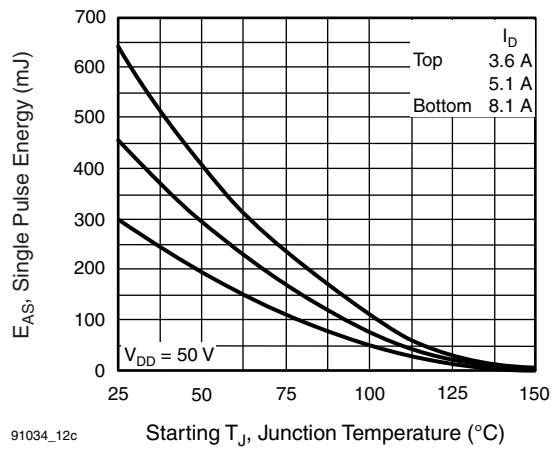


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

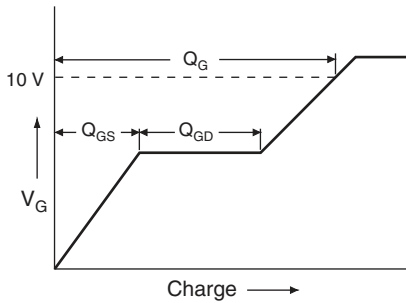


Fig. 13a - Basic Gate Charge Waveform

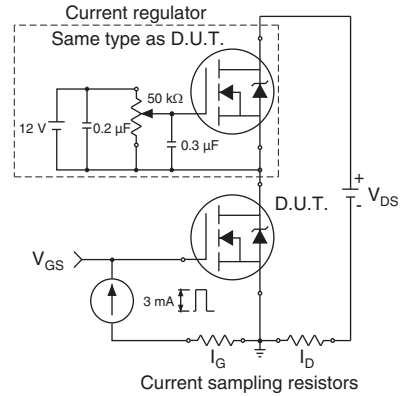
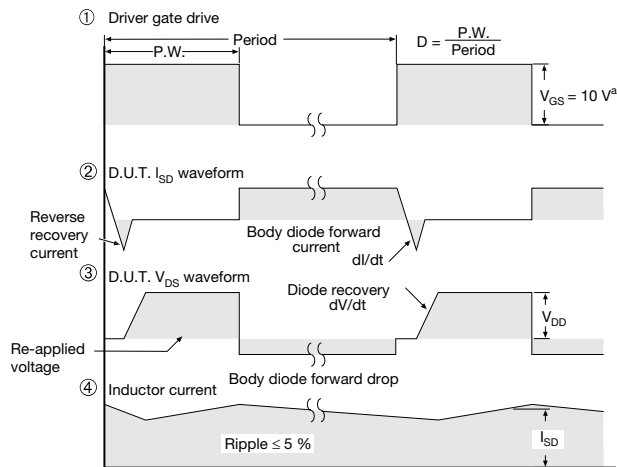
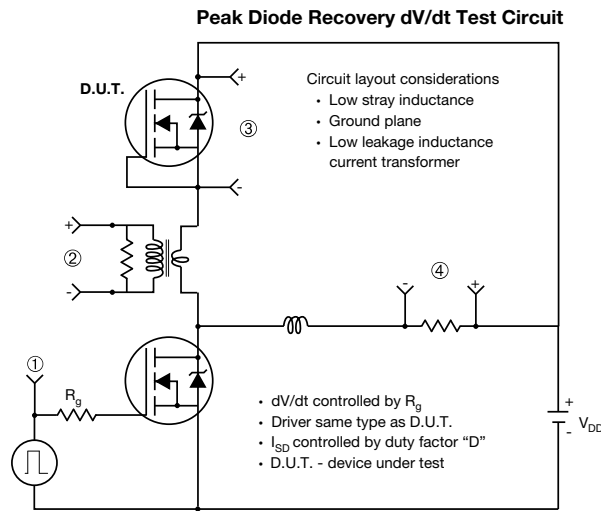


Fig. 13b - Gate Charge Test Circuit



**Note**  
a.  $V_{GS} = 5\text{ V}$  for logic level devices

Fig. 14 - For N-Channel

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